HD74HCT564, HD74HCT574

Octal D-type Flip-Flops (with 3-state outputs)

REJ03D0670–0200
(Previous ADE-205-560)
Rev.2.00
Mar 30, 2006

Description

These devices are positive edge triggered flip-flops. The difference between HD74HCT564 and HD74HCT574 is only that the former has inverting outputs and the latter has noninvertering outputs.

Data at the D inputs, meeting the set-up and hold time requirements, are transferred to the Q or $\overline{Q}$ outputs on positive going transitions of the clock (CK) input. when a high logic level is applied to the output control (OC) input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements.

Features

- LSTTL Output Logic Level Compatibility as well as CMOS Output Compatibility
- High Speed Operation: t_{pd} (D to Q, $\overline{Q}$) = 15 ns typ (C_L = 50 pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage: V_{CC} = 4.5 to 5.5 V
- Low Input Current: 1 µA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 µA max (Ta = 25°C)
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HCT564P HD74HCT574P	DILP-20 pin	PRDP0020AC-B (DP-20NEV)	P	—
HD74HCT564FPEL HD74HCT574FPEL	SOP-20 pin (JEITA)	PRSP0020DD-B (FP-20DAV)	FP	EL (2,000 pcs/reel)
HD74HCT564RPEL HD74HCT574RPEL	SOP-20 pin (JEDEC)	PRSP0020DC-A (FP-20DBV)	RP	EL (1,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Function Table

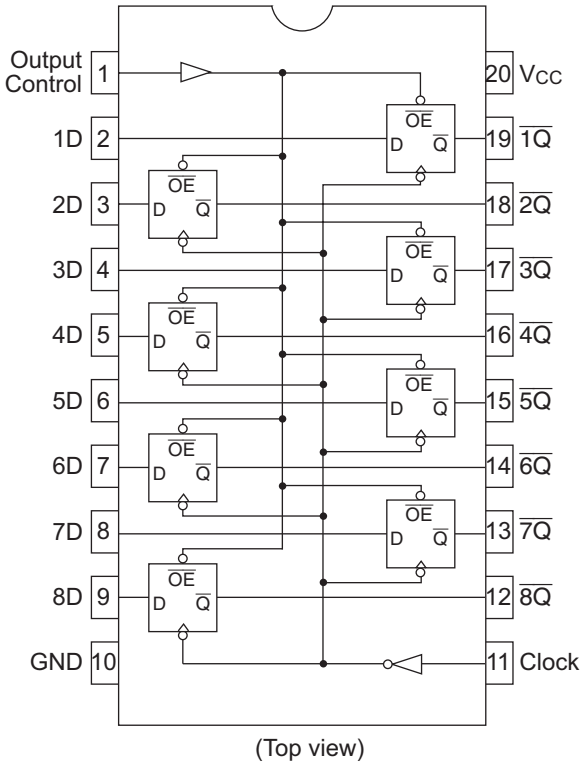
Inputs			Outputs	
Output Control	Clock	Data	HD74HCT564	HD74HCT574
L	↑	H	L	H
L	↑	L	H	L
L	L	X	Q_0	Q_0
H	X	X	Z	Z

Q_0 : level of Q before the indicated Steady-sate input conditions were established.

$\overline{Q}_0$: complement of Q_0 or level of $\overline{Q}$ before the indicated Steady-state input Conditions were established.

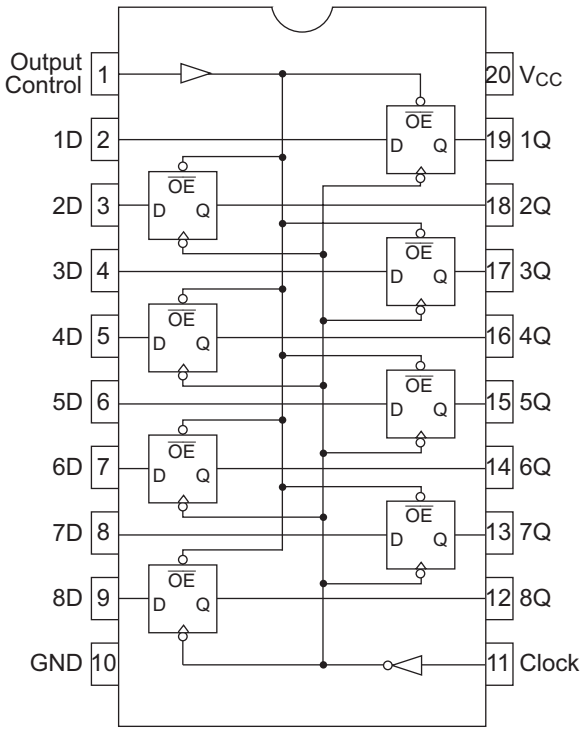
Pin Arrangement

HD74HC564



(Top view)

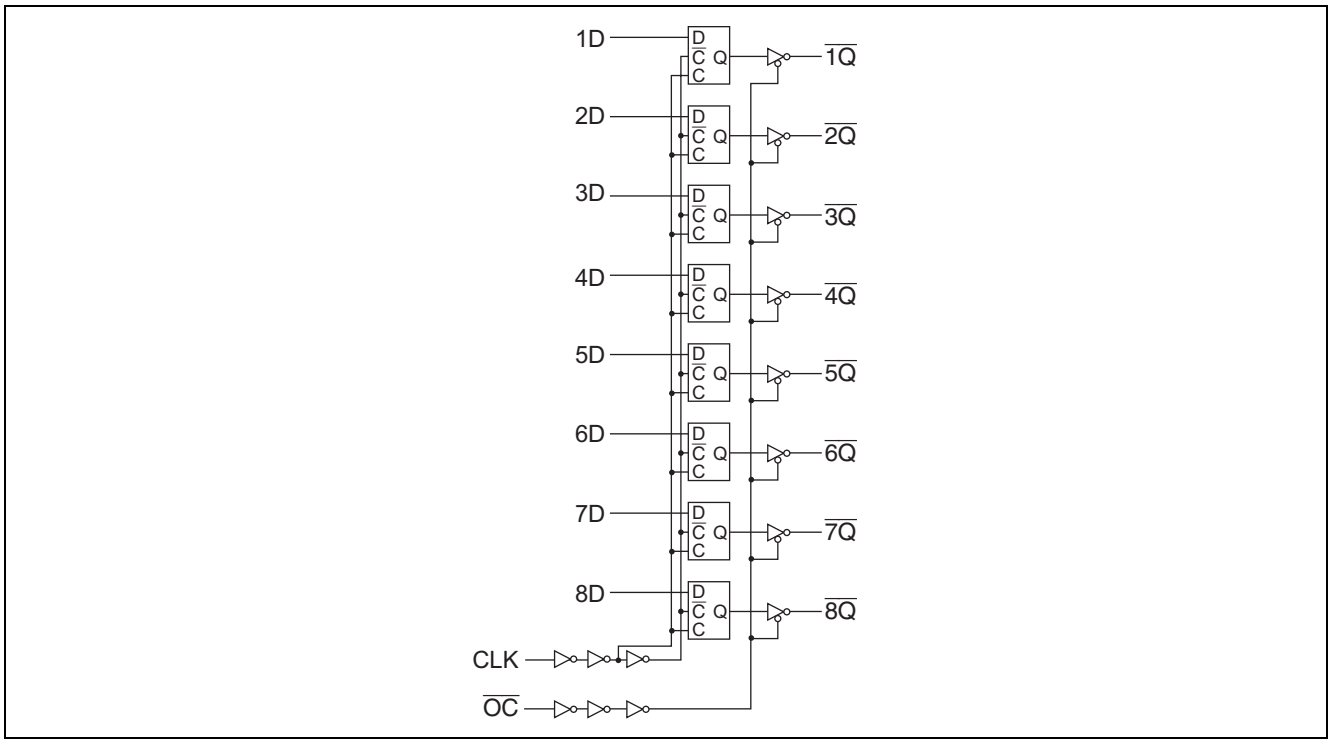
HD74HC574



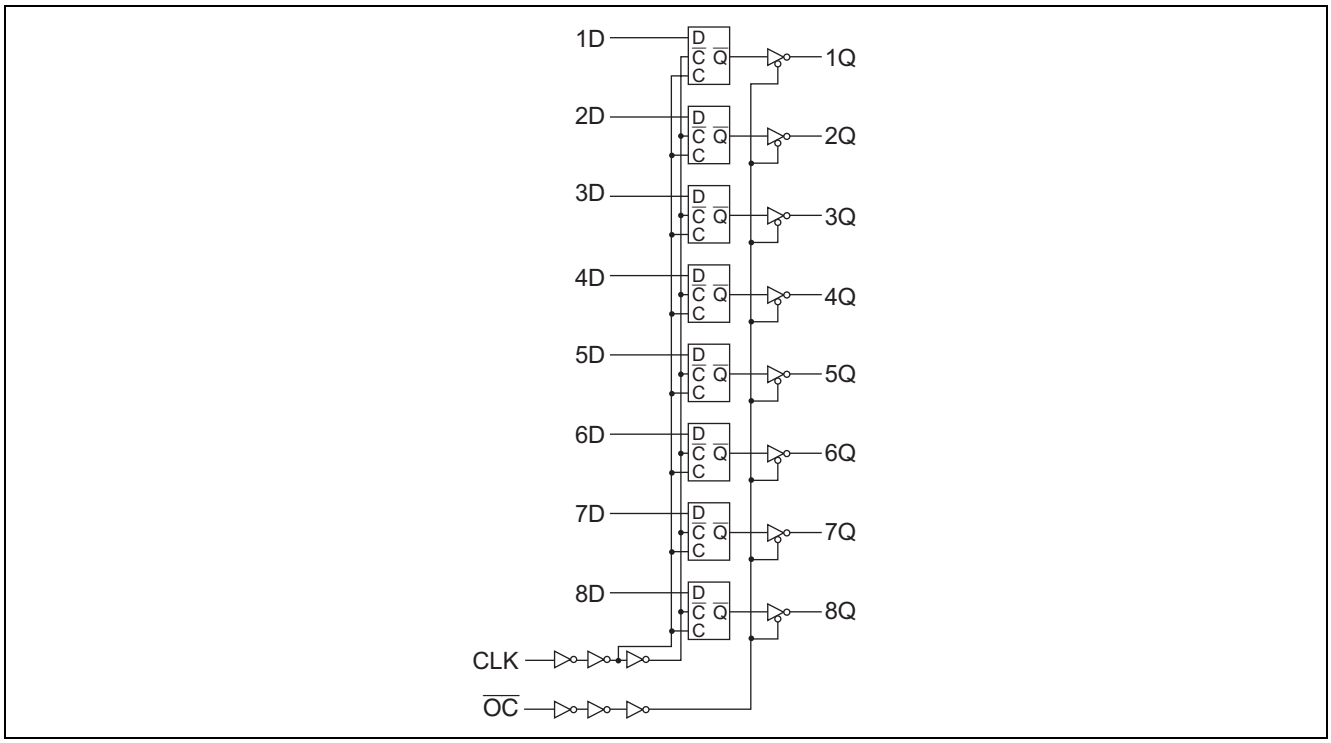
(Top view)

Logic Diagram

HD74HC564



HD74HC574



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V_{CC}	–0.5 to 7.0	V
Input / Output voltage	V_{IN}, V_{OUT}	–0.5 to V_{CC} +0.5	V
Input / Output diode current	I_{IK}, I_{OK}	±20	mA
Output current	I_O	±35	mA
V_{CC}, GND current	I_{CC} or I_{GND}	±75	mA
Power dissipation	P_T	500	mW
Storage temperature	Tstg	–65 to +150	°C

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	4.5 to 5.5	V	
Input / Output voltage	V_{IN}, V_{OUT}	0 to V_{CC}	V	
Operating temperature	Ta	–40 to 85	°C	
Input rise / fall time[*1]	t_r, t_f	0 to 500	ns	V_{CC} = 4.5 V

Notes: 1. This item guarantees maximum limit when one input switches.
Waveform: Refer to test circuit of switching characteristics.

Electrical Characteristics

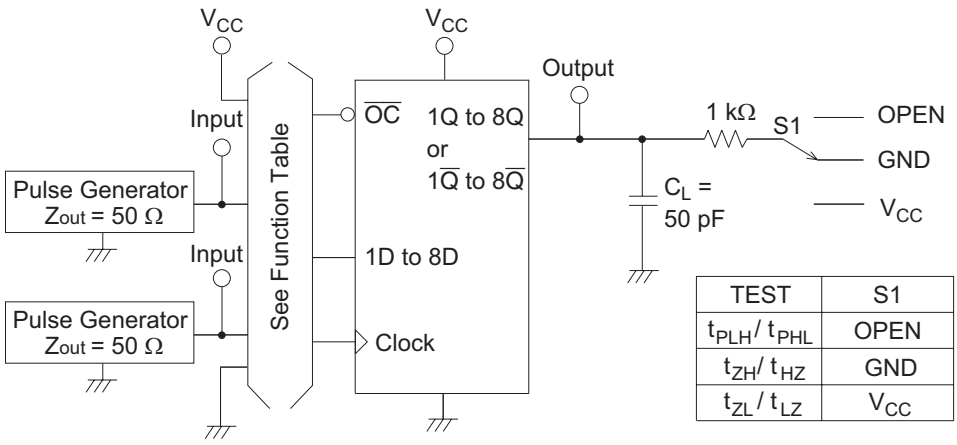
Item	Symbol	V_{CC} (V)	Ta = 25°C			Ta = –40 to+85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V_{IH}	4.5 to 5.5	2.0	—	—	2.0	—	V		
	V_{IL}	4.5 to 5.5	—	—	0.8	—	0.8	V		
Output voltage	V_{OH}	4.5	4.4	—	—	4.4	—	V	Vin = V_{IH} or V_{IL}	I_{OH} = –20 µA
		4.5	4.18	—	—	4.13	—			I_{OH} = –6 mA
	V_{OL}	4.5	—	—	0.1	—	0.1	V	Vin = V_{IH} or V_{IL}	I_{OL} = 20 µA
		4.5	—	—	0.26	—	0.33			I_{OL} = 6 mA
Off-state output current	I_{OZ}	5.5	—	—	±0.5	—	±5.0	µA	Vin = V_{IH} or V_{IL}, Vout = V_{CC} or GND	
Input current	Iin	5.5	—	—	±0.1	—	±1.0	µA	Vin = V_{CC} or GND	
Quiescent current	I_{CC}	5.5	—	—	4.0	—	40	µA	Vin = V_{CC} or GND, Iout = 0 µA	

Switching Characteristics

(C_L = 50 pF, Input t_r = t_f = 6 ns)

Item	Symbol	V_{CC} (V)	Ta = 25°C			Ta = –40 to +85°C		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Maximum clock frequency	f_{max}	4.5	—	—	30	—	24	ns	
Propagation delay time	t_{PLH}	4.5	—	14	31	—	39	ns	
	t_{PHL}	4.5	—	15	31	—	39		
Output enable time	t_{ZL}	4.5	—	16	30	—	38	ns	
	t_{ZH}	4.5	—	16	30	—	38		
Output disable time	t_{LZ}	4.5	—	15	30	—	38	ns	
	t_{HZ}	4.5	—	18	30	—	38		
Setup time	t_{su}	4.5	20	3	—	25	—	ns	
Hold time	t_h	4.5	5	–2	—	5	—	ns	
Pulse width	t_w	4.5	16	7	—	20	—	ns	
Output rise/fall time	t_{TLH}	4.5	—	4	12	—	15	ns	
	t_{THL}	4.5	—	4	12	—	15		
Input capacitance	Cin	—	—	5	10	—	10	pF	

Test Circuit

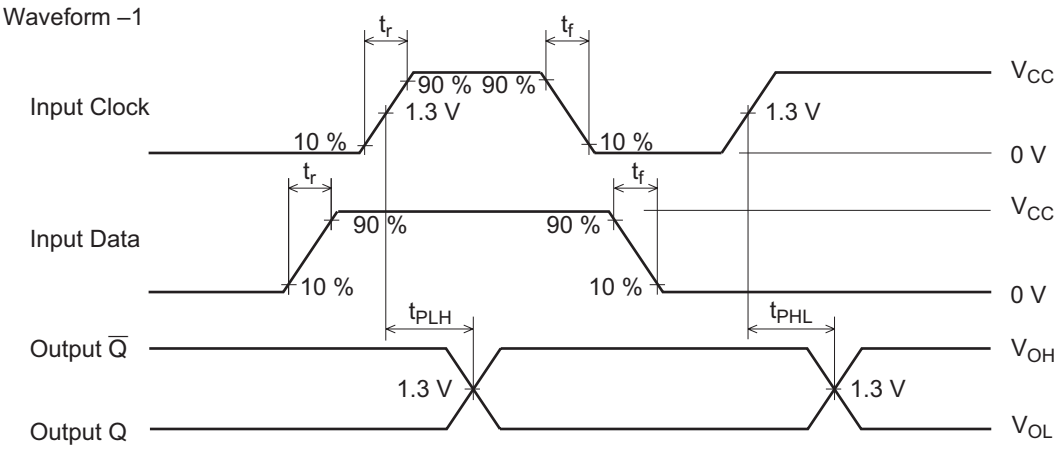


TEST	S1
t_{PLH} / t_{PHL}	OPEN
t_{ZH} / t_{HZ}	GND
t_{ZL} / t_{LZ}	V_{CC}

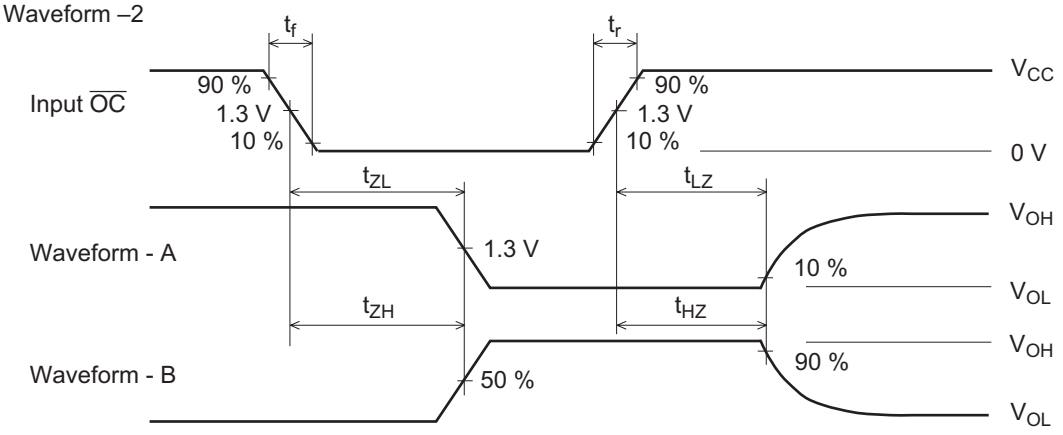
Note : 1. C_L includes probe and jig capacitance.

Waveforms

• Waveform –1



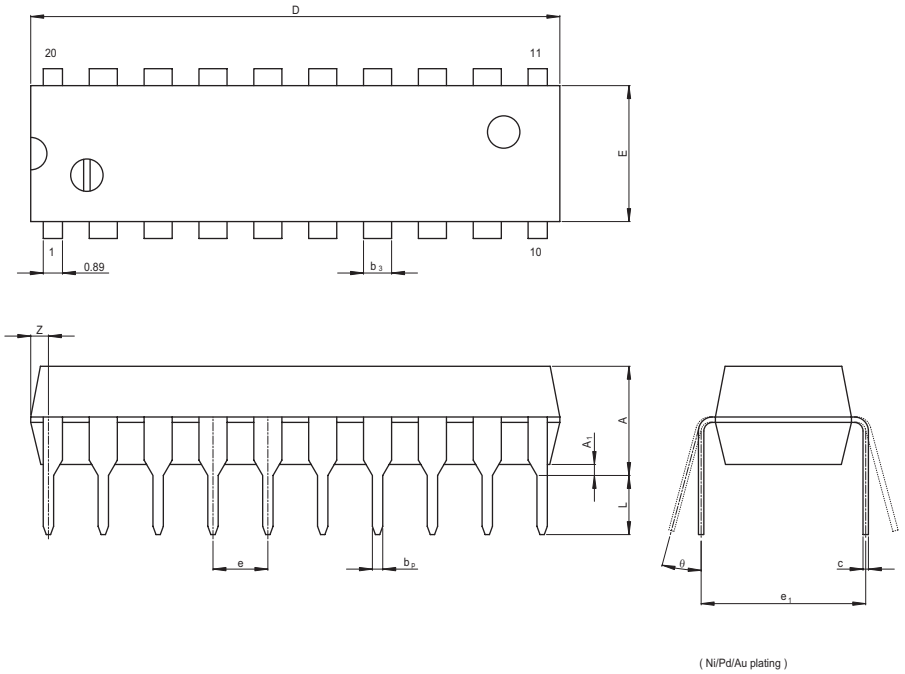
• Waveform –2



Notes : 1. Input waveform : PRR ≤ 1 MHz, duty cycle 50%, t_r ≤ 6 ns, t_f ≤ 6 ns
2. Waveform– A is for an output with internal conditions such that the output is low except when disabled by the output control.
3. Waveform– B is for an output with internal conditions such that the output is high except when disabled by the output control.
4. The output are measured one at a time with one transition per measurement.

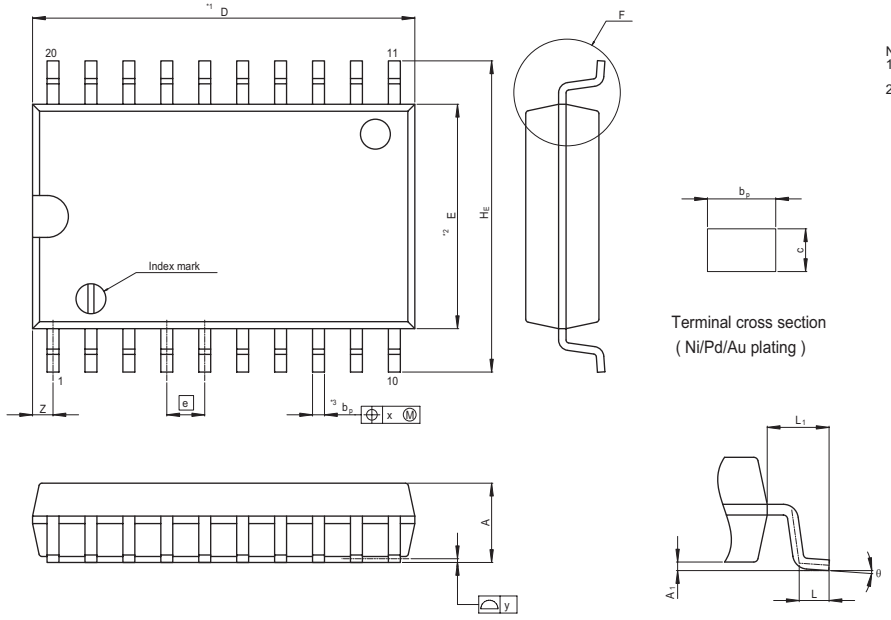
Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-DIP20-6.3x24.5-2.54	PRDP0020AC-B	DP-20NEV	1.26g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e_1	—	7.62	—
D	—	24.50	25.40
E	—	6.30	7.00
A	—	—	5.08
A_1	0.51	—	—
b_p	0.40	0.48	0.56
b_3	—	1.30	—
c	0.19	0.25	0.31
θ	0°	—	15°
e	2.29	2.54	2.79
Z	—	—	1.27
L	2.54	—	—

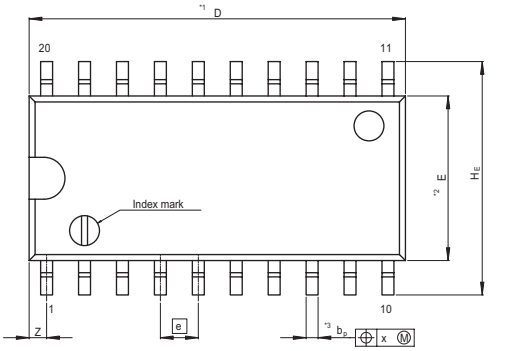
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP20-7.5x12.8-1.27	PRSP0020DC-A	FP-20DBV	0.52g

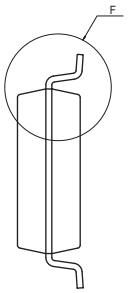


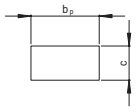
NOTE)
1. DIMENSIONS"*1 (Nom)"AND"*2"
@ DO NOT INCLUDE MOLD FLASH.
2. DIMENSION"*3"DOES NOT
@ INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	12.80	13.2
E	—	7.50	—
A_2	—	—	—
A_1	0.10	0.20	0.30
A	—	—	2.65
b_p	0.34	0.40	0.46
b_1	—	—	—
c	0.20	0.25	0.30
c_1	—	—	—
θ	0°	—	8°
H_E	10.00	10.40	10.65
e	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.935
L	0.40	0.70	1.27
L_1	—	1.45	—

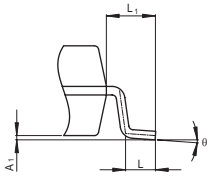
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP20-5.5x12.6-1.27	PRSP0020DD-B	FP-20DAV	0.31g







Terminal cross section
(Ni/Pd/Au plating)



Detail F

NOTE)
1. DIMENSIONS"*1 (Nom)"AND"*2"
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION"*3"DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	12.60	13.0
E	—	5.50	—
A_2	—	—	—
A_1	0.00	0.10	0.20
A	—	—	2.20
b_p	0.34	0.40	0.46
b_1	—	—	—
c	0.15	0.20	0.25
c_1	—	—	—
θ	0°	—	8°
H_E	7.50	7.80	8.00
e	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L_1	—	1.15	—

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